Claims:

1. A flux comprising one or more amines, wherein the flux comprises:
from 10 to 40 % by weight monoethanol amine,
from 15 to 30 % by weight triethanol amine,
from 10 to 35 % by weight aminoethylethanol amine,
from 5 to 20 % by weight ethoxylated tallow amines, and
from 1 to 10 % by weight ethoxylated polyamine.

2. The flux of claim 1 comprising an activator, wherein the activator is selected from one or more of zinc chloride, aluminium chloride and fluoroboric acid.

3. The flux of claim 2 comprising:
from 1 to 5 % by weight aluminium chloride and/or
from 5 to 15 % by weight zinc chloride, and/or
from 5 to 15 % by weight fluoroboric acid.

4. The flux of any preceding claim further comprising a surfactant, preferably selected from octyl phenol ethoxylates and nonyl phenol ethoxylates.

5. The flux of any preceding claim comprising:
from 1 to 5 wt.% water;
from 1 to 5 wt.% ammonium chloride;
from 5 to 15 wt.% zinc chloride;
from 5 to 15 wt.% fluoroboric acid, 50%;
from 1 to 5 wt.% tin fluoroborate; and
from 1 to 5 wt.% nonyl and/or octyl phenolethyloxate.

6. The flux of any preceding claim comprising:
from 1 to 5 wt.% water;
from 1 to 5 wt.% ammonium chloride;

from 5 to 15 wt.% zinc chloride;
from 5 to 15 wt.% fluoroboric acid, 50%; and
from 1 to 5 wt.% tin fluoroborate.

7. A solder paste comprising the flux of any preceding claim, wherein the solder paste comprises solder particles selected from one or more of: tin, tin-silver alloy, tin-silver-copper alloy, tin-bismuth alloy and tin-silver-bismuth alloy.

8. A soldered joint manufactured using the flux of any of claims 1 to 6 or the paste of claim 7.

9. A method of processing an aluminium surface comprising:
providing an aluminium surface;
contacting the aluminium surface with a flux as described in any of claims 1 to 6 followed by contacting the aluminium surface with a molten liquid comprising tin or tin alloy.

10. The method of claim 9 further comprising washing the aluminium surface after contacting the aluminium substrate with the molten liquid.

11. The method of claim 9 or claim 10, wherein the step of contacting the aluminium surface with a flux comprises spraying and/or dipping and/or brushing.

12. The method of any of claims 9 to 11, wherein the step of contacting the aluminium surface with a molten liquid comprising tin or tin alloy comprises hot air solder levelling and/or wave soldering.

13. The method of any of claims 9 to 12 further comprising applying solder to the aluminium surface.

14. Use of the flux of any of claims 1 to 6 or the solder paste of claim 7 in the manufacture of a device selected from: a printed circuit board, an LED and a photovoltaic module.